

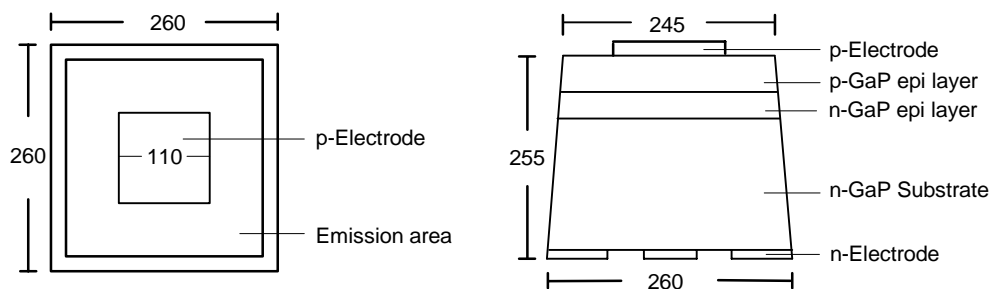
■ Features :

- GaP Epi Wafer

■ Typical Applications :

- Lamp
- SMD
- Display

■ Outline Dimensions : (Unit: μm)



■ Physical Structure :

Chip dimension	Chip size	260 μm x 260 μm
	Thickness	255 μm
	Emission area	245 μm
	Bonding pad	110 μm
Electrode	Top: P (anode)	Aluminum (Gold optional)
	Backside: N (cathode)	Gold alloy
Surface condition	Frosted	

■ Electro-Optical Characteristics : ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 20\text{ mA}$	1.80	2.20	2.60	V
Reverse Current	I_R	$V_R = 5\text{ V}$	-	-	10	μA
Wavelength	P	$I_F = 20\text{ mA}$	-	565	-	nm
	Hue		-	570	-	
Spectral width at half height		$I_F = 20\text{ mA}$	-	26	-	nm
Luminous Intensity	I_V	$I_F = 20\text{ mA}$	4.0	7.0	-	mcd

■ **Typical Electro-Optical Characteristics Curve:**

Fig 1. Forward Current vs. Forward Voltage

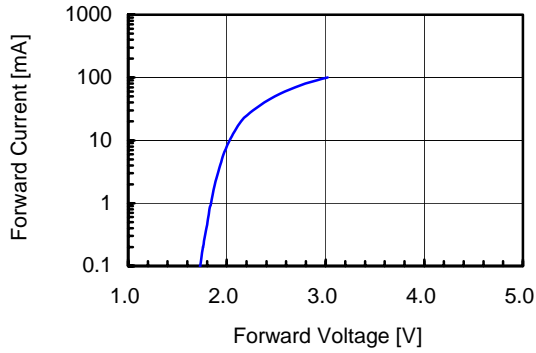


Fig 2. Relative Intensity vs. Forward Current

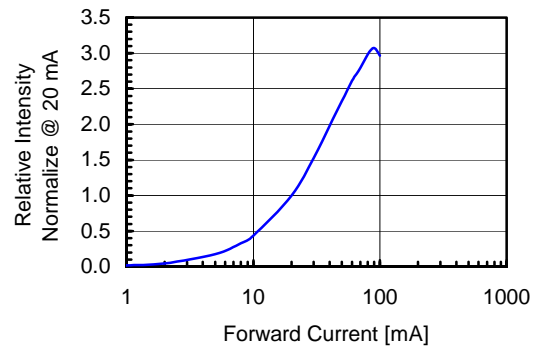


Fig 3. Forward Voltage vs. Temperature

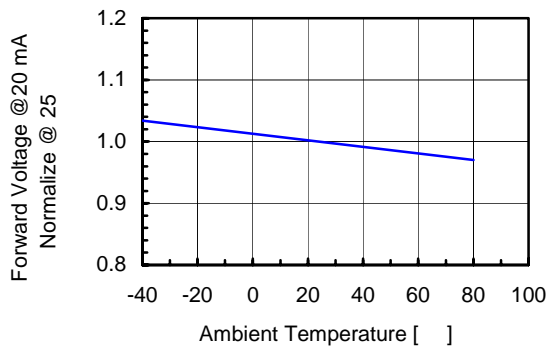


Fig4. Relative Intensity vs. Temperature

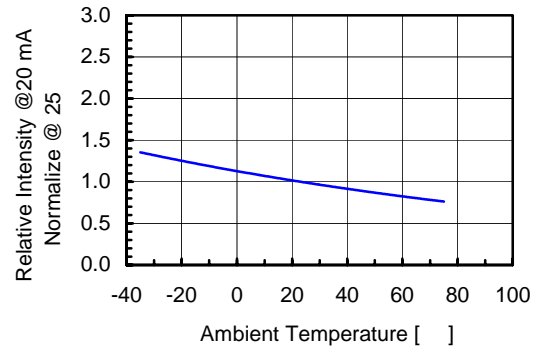


Fig 5. Relative Intensity vs. Wavelength

